

P-Channel POWER MOSFET

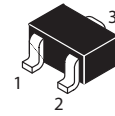
 Lead(Pb)-Free

Description:

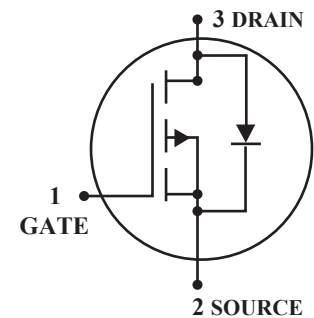
* These miniature surface mount MOSFETs reduce power loss conserve energy, making this device ideal for use in small power management circuitry. Typical applications are dc-dc converters, load switching, power management in portable and battery-powered products such as computers, printers, cellular and cordless telephones.

Features:

- * Simple Drive Requirement
- * Small Package Outline



SOT-323(SC-70)



Maximum Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Specified)

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DDS}	50	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current $V_{\text{GS}} = (T_A=25^\circ\text{C})$	I_{D}	130	mA
Pulsed Drain Current ($t_p \leq 10\mu\text{s}$)	I_{DM}	520	mA
Total Power Dissipation ($T_A=25^\circ\text{C}$)	P_{D}	225	mW
Thermal Resistance – Junction-to-Ambient	$R_{\theta\text{JA}}$	556	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	T_{J}	-55 to +150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^\circ\text{C}$
Maximum Lead Temperature for Soldering Purposes, for 10 seconds	T_{L}	260	$^\circ\text{C}$

Device Marking

BSS84W = PD

Electrical Characteristics (T_A=25°C Unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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Static

Drain-Source Breakdown Voltage V _{GS} =0V, I _D =250μA	V _{(BR)DSS}	50	-	-	V
Gate-Source Threshold Voltage V _{DS} =V _{GS} , I _D =1.0mA	V _{GS(th)}	0.8	-	2.0	V
Gate-Body Leakage Current V _{GS} =±20V, V _{DS} =0	I _{GSS}	-	-	±60	μA
Zero Gate Voltage Drain Current V _{DS} =25V, V _{GS} =0 V _{DS} =50V, V _{GS} =0 V _{DS} =50V, V _{GS} =0, T _J = 125°C	I _{DSS}	- - -	- - -	0.1 15 60	μA
Static Drain-Source On-Resistance V _{GS} =5.0V, I _D =100mA	R _{DS(on)}	-	5.0	10	Ω
Transfer Admittance V _{DS} =25V, I _D =100mA, f = 1.0kHz	y _{fs}	50	-	-	mS

Dynamic

Input Capacitance V _{DS} =5.0V	C _{iss}	-	30	-	pF
Output Capacitance V _{DS} =5.0V	C _{oss}	-	10	-	
Reverse Transfer Capacitance V _{DS} =5.0V	C _{rss}	-	5.0	-	

Switching²

Turn-On Delay Time V _{DD} =-15V, I _D =-2.5A, R _L =50Ω	td(on)	-	2.5	-	ns
Rise Time V _{DD} =-15V, I _D =-2.5A, R _L =50Ω	tr	-	1.0	-	
Turn-Off Delay Time V _{DD} =-15V, I _D =-2.5A, R _L =50Ω	td(off)	-	16	-	
Fall Time V _{DD} =-15V, I _D =-2.5A, R _L =50Ω	tf	-	8.0	-	
Gate Charge	Q _T	-	6000	-	pC

Source-Drain Diode

Continuous Current	I _S	-	-	0.130	A
Pulsed Current	I _{SM}	-	-	0.520	
Forward Voltage (Note 2.)	V _{SD}	-	2.5	-	V

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

2. Switching characteristics are independent of operating junction temperature.

TYPICAL ELECTRICAL CHARACTERISTICS

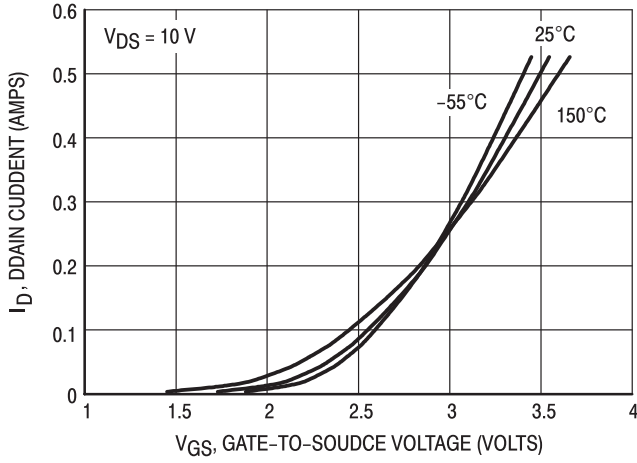


Figure 1. Transfer Characteristics

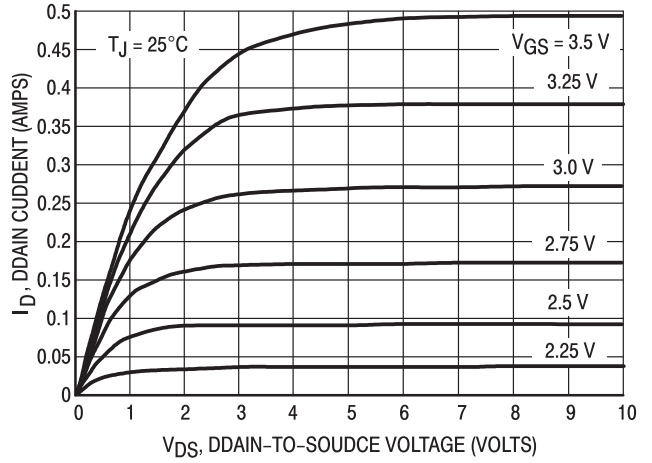


Figure 2. On-Region Characteristics

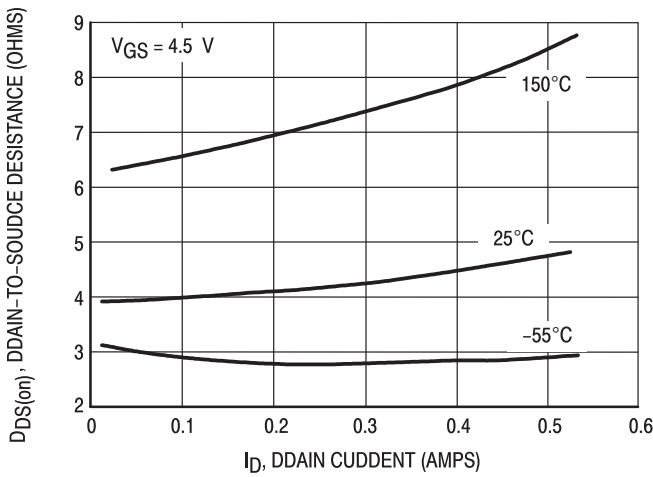


Figure 3. On-Resistance versus Drain Current

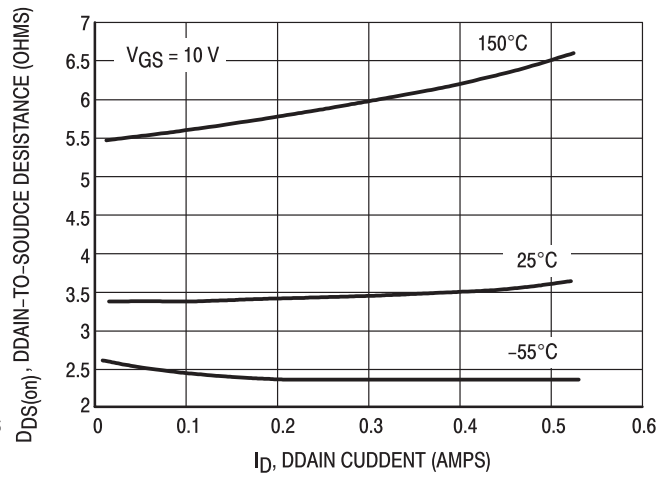


Figure 4. On-Resistance versus Drain Current

TYPICAL ELECTRICAL CHARACTERISTICS

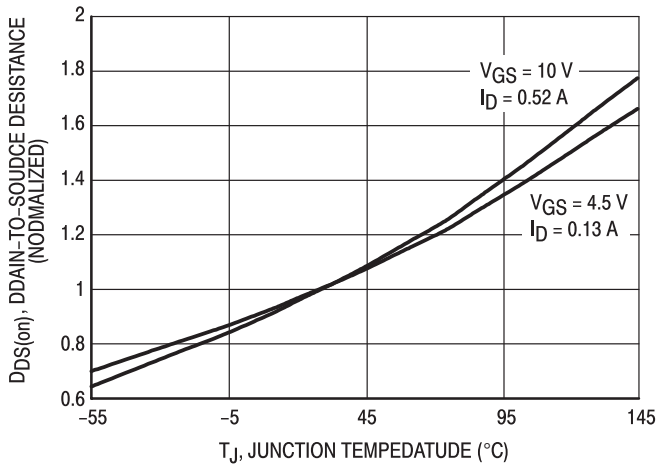


Figure 5. On-Resistance Variation with Temperature

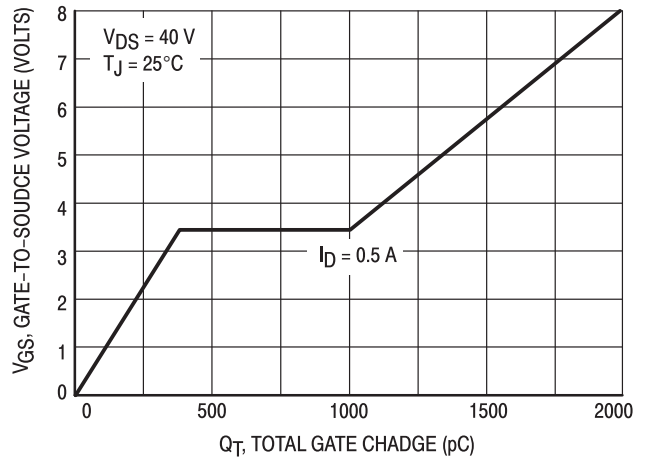


Figure 6. Gate Charge

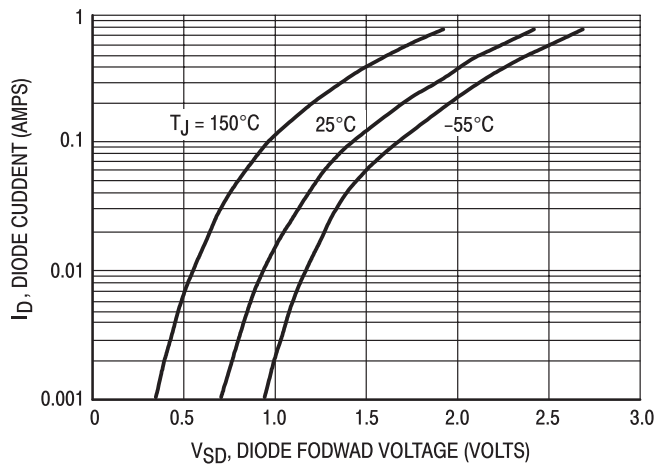
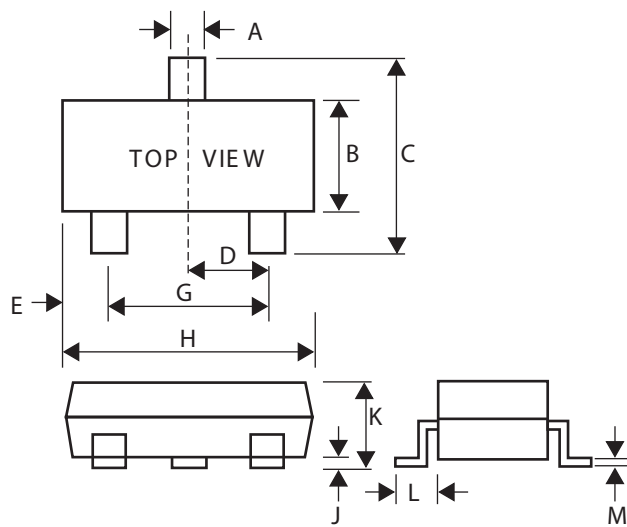


Figure 7. Body Diode Forward Voltage

SOT-323 Outline Demensions

Unit:mm



SOT-323		
Dim	Min	Max
A	0.30	0.40
B	1.15	1.35
C	2.00	2.40
D	-	0.65
E	0.30	0.40
G	1.20	1.40
H	1.80	2.20
J	0.00	0.10
K	0.80	1.00
L	0.42	0.53
M	0.10	0.25